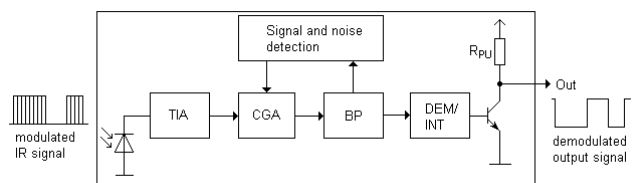


DATASHEET

Infrared Receiver Control Receiver Module EAIRMLA3



Block Diagram



Features

- High shielding against electric field disturbance.
- Circular lens to improve the receive characteristic.
- Line-up for various center carrier frequencies.
- Low voltage and low power consumption.
- High immunity against ambient light.
- Photodiode with integrated circuit.
- TTL and CMOS compatibility.
- Side-received SMD.
- Suitable burst length ≥ 10 pulses/burst.
- This product itself will remain within RoHS compliant version.
- Pb free.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

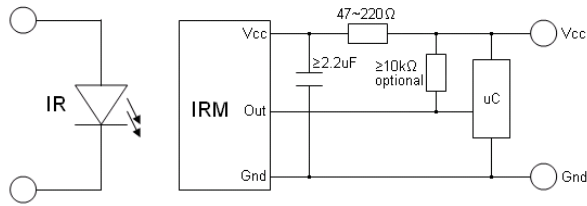
Description

- The device is miniature SMD type infrared receiver that has been developed and designed by utilizing the latest IC technology.
- The PIN diode and preamplifier are assembled onto a lead frame and molded into an epoxy package which operated an IR filter. The demodulated output signal can directly be decoded by a microprocessor.

Applications

- Light detecting portion of remote control
- AV instruments such as Audio, TV, VCR, CD, MD, etc
- Home appliances such as Air-conditioner, Fan, etc
- Other devices using IR remote control
- CATV set top boxes
- Multi-media Equipment

Application Circuit



Parts Table

Model No.	Carrier Frequency
EAIRMLA3	38 kHz

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Supply Voltage	Vcc	6	V
Operating Temperature	Topr	-20 ~ +80	°C
Storage Temperature	Tstg	-40 ~ +85	°C

*1 4mm from mold body for less than 5 seconds

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current consumption	I _{CC}	-	-	1.2	mA	No input signal
Supply voltage	V _{CC}	2.7	-	5.5	V	
Peak wavelength	λ _p	---	940	---	nm	
Reception range	L ₀	8	---	---	m	
	L ₄₅	5	---	---		
Half angle(horizontal)	φ _h	---	±45	---	deg	At the ray axis *1
Half angle(vertical)	φ _v	---	±45	---	deg	
High level pulse width	T _H	400	-	800	μs	At the ray axis *2
Low level pulse width	T _L	400	-	800	μs	
High level output voltage	V _{OH}	2.7	---	---	V	
Low level output voltage	V _{OL}	---	0.2	0.5	V	

Notes:

*1 : The ray receiving surface at a vertex and relation to the ray axis in the range of θ= 0° and θ=45°.

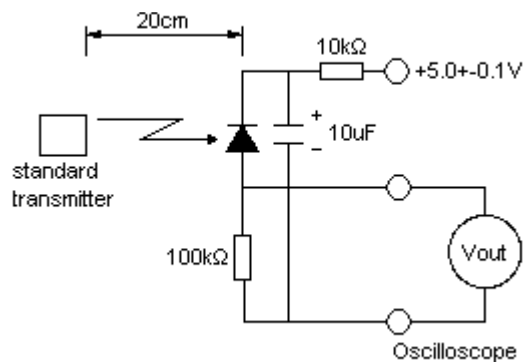
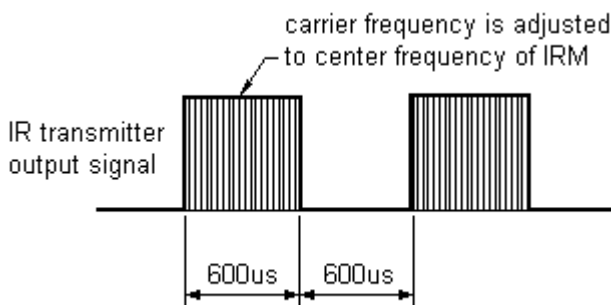
*2 : A range from 30cm to the arrival distance. Average value of 50 pulses.

Test method

The specified electro-optical characteristics are valid under the following conditions.

1. Measurement environment
A place without extreme light reflections.
2. External light
The environment contains an ordinary, white fluorescent lamp without high frequency modulation. The color temperature is 2856K and the illumination at the IR receiver is less than 10 Lux ($E_v \leq 10\text{Lux}$).
3. Standard transmitter
The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until $V_o = 400\text{mVp-p}$. Both, the test transmitter and the photo diode, have a peak wavelength of 940nm. The photo diode for calibration is PD438B ($\lambda_p = 940\text{nm}$, $V_r = 5\text{V}$).
4. The measurement system is shown in Fig.-3

Fig.-1 Transmitter Wave Form



D.U.T output Pulse

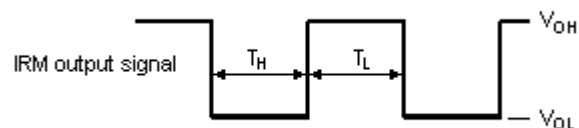
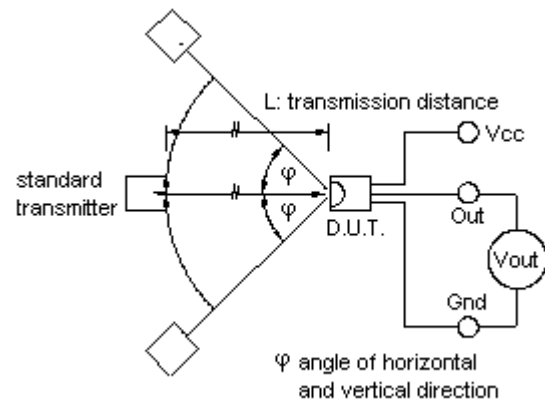


Fig.-3 Measuring System



Typical Electro-Optical Characteristics Curves

Fig.-4 Relative Spectral Sensitivity vs. Wavelength

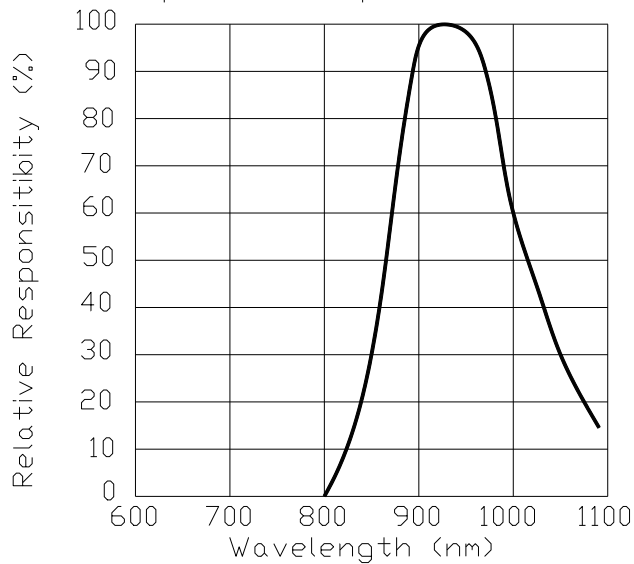


Fig.-5 Relative Transmission Distance vs. Direction

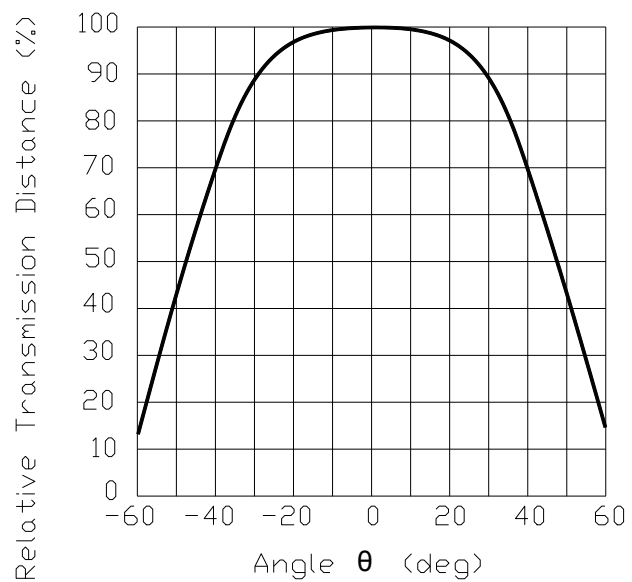


Fig.-6 Output Pulse Length vs. Arrival Distance

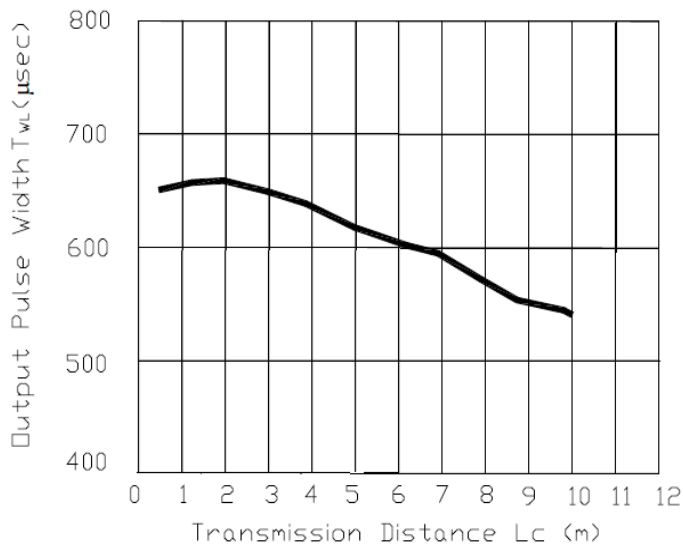


Fig.-7 Arrival Distance vs. Supply Voltage

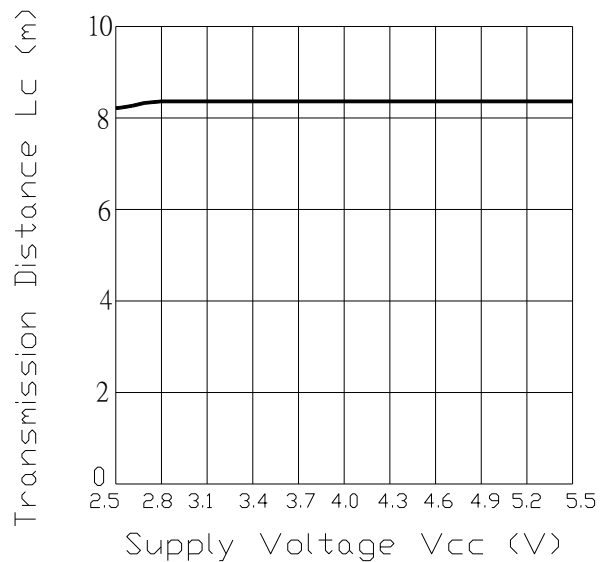
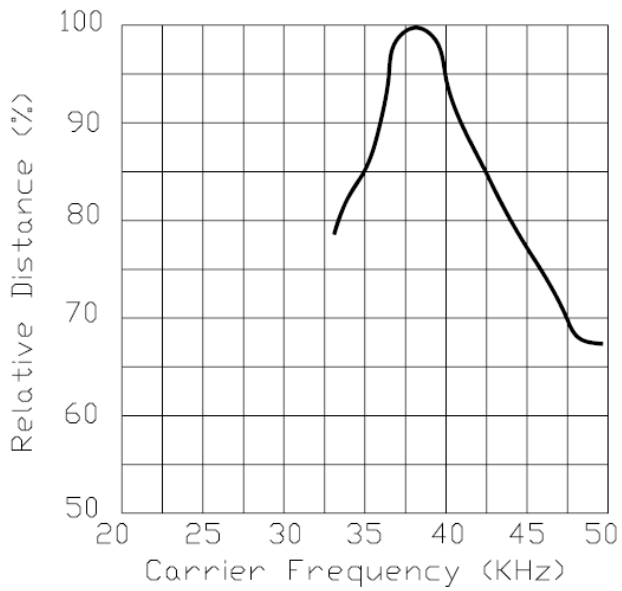
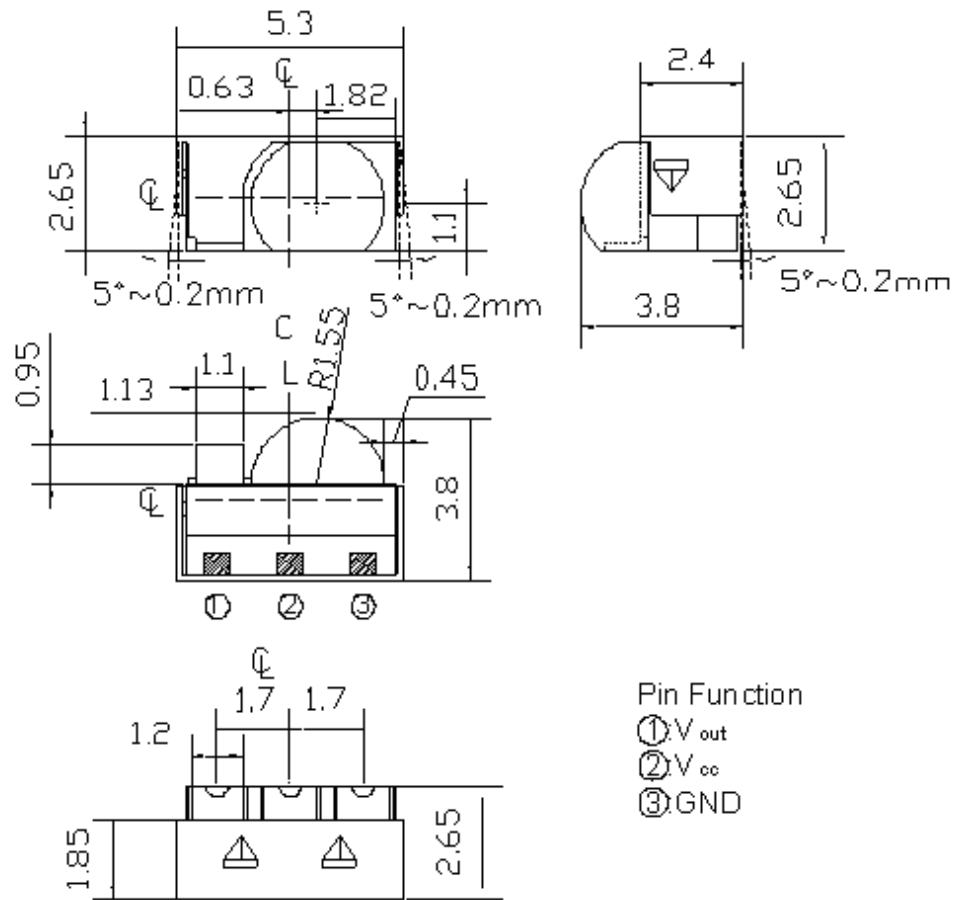


Fig.-8 Relative Transmission Distance vs. Center Carrier Frequency



Package Dimension
(Dimensions in mm)

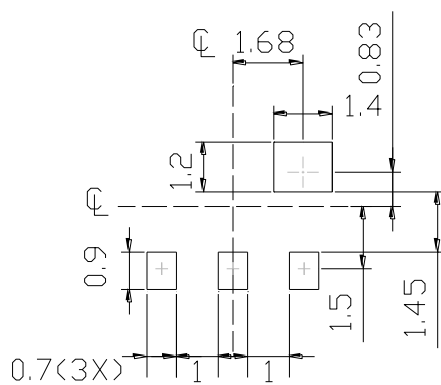


Pin Function

- ① V_{out}
- ② V_{cc}
- ③ GND

Note : Tolerances unless dimensions ± 0.3 mm.

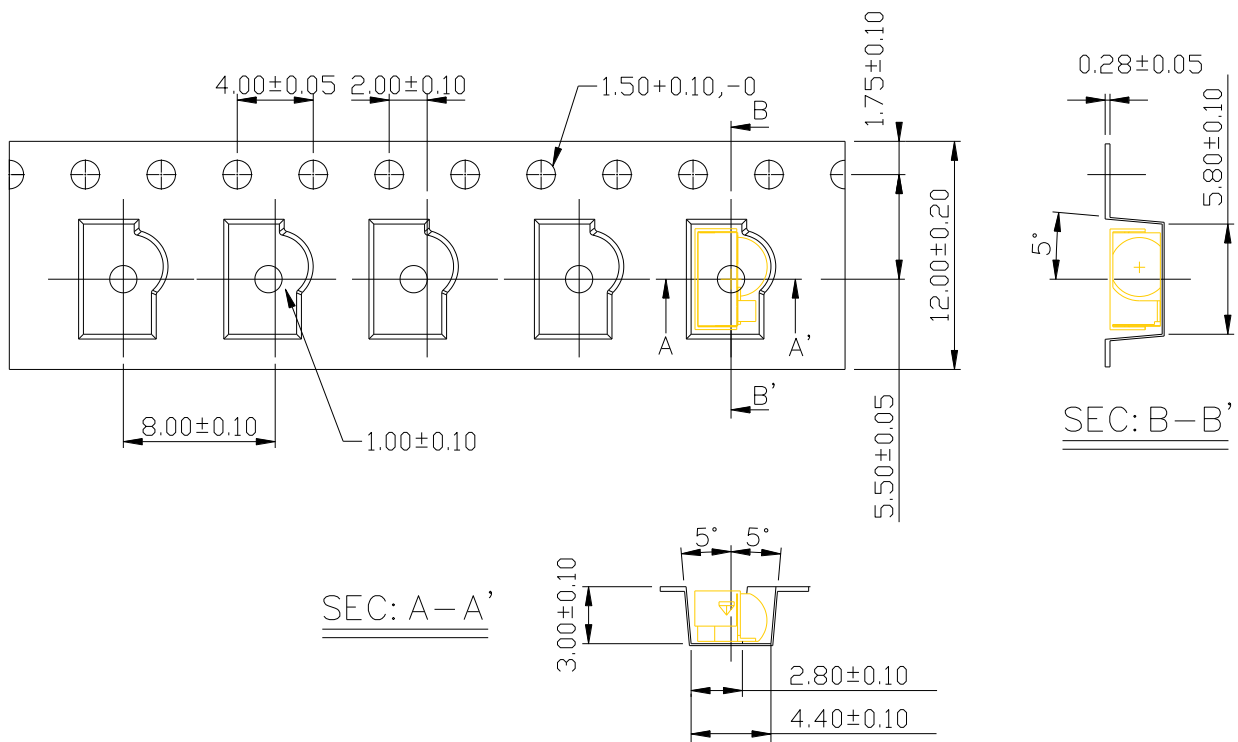
Recommended pad layout for surface mount leadform



Code information

Protocol	Suitable	Protocol	Suitable
JVC	No	RCA	No
Matsushita	Yes	Sharp	Yes
Mitsubishi	No	Sony 12 Bit	Yes
NEC	Yes	Sony 15 Bit	No
RC5	Yes	Sony 20 Bit	No
RC6	Yes	Toshiba	Yes
RCMM	No	Zenith	Yes
RCS-80	No	Continuous Code	No

Tape & Reel Packing Specifications (Dimensions in mm)



Packing Quantity

2000 pcs / Reel
5 Reels / Carton

Label format

	EVERLIGHT
CPN:	
P/N: 30XXXXXXXX	
	RoHS
IRM-XXXX/TRX	
QTY: 2000	CAT:
	HUE:
LOT NO:	REF:
	
MADE IN CHINA	

	Caution This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL 
If blank, see adjacent bar code label		
1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)		
2. Peak package body temperature: _____ °C If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must		
a) Mounted within: _____ hours of factory conditions If blank, see adjacent bar code label		
<30°C/60% RH, OR		
b) Stored at <10% RH		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card is >10% when read at 23 ± 5°C		
b) 3a or 3b not met		
5. If baking is required, devices may be baked for 48 hours at 125 ± 5°C		
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

Moisture Classification-storage and used condition label

Recommended method of storage

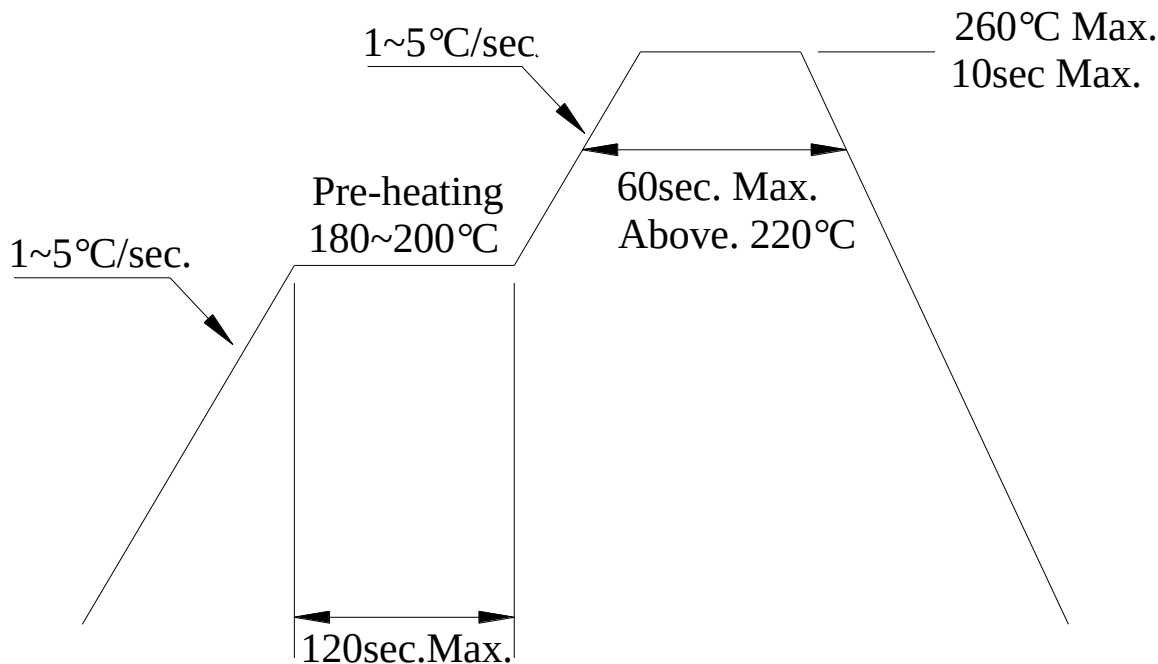
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

1. Shelf life in sealed bag from the bag seal date: 12 months at < 40 °C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must mounted within 72 hours of factory conditions < 30 °C/60%RH.
3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions: 60±5°C for 96 hours.

ESD Precaution

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

Solder Reflow Temperature Profile



Note:

1. Reflow soldering should not be done more than two times.
2. When soldering, do not put stress on the IRM device during heating.
3. After soldering, do not warp the circuit board.

Application Restrictions

1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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